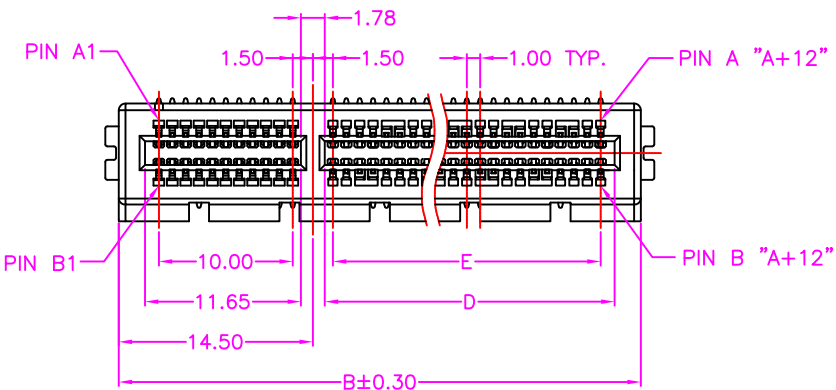


SECTION: G-G

MATERIALS

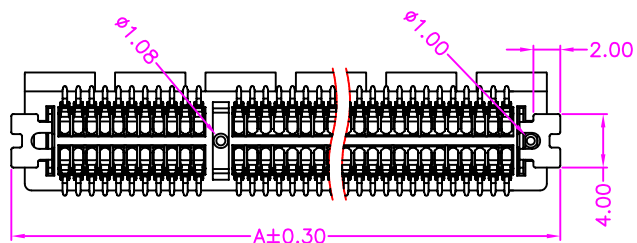
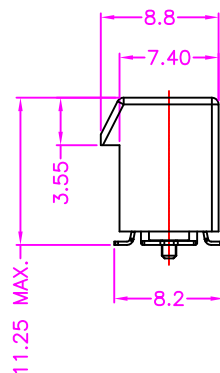
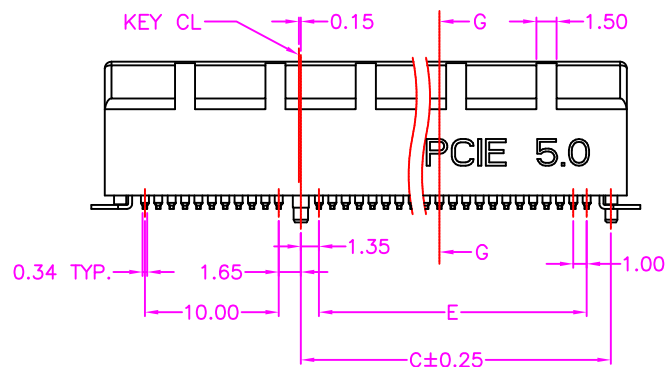
HOUSING: PA9T (UL 94V-0), BLACK
SOLDER PAD: COPPER ALLOY, TIN PLATING
TERMINAL: COPPER ALLOY, GOLD PLATED ON CONTACT AREA
TIN PLATING ON SOLDER TAIL

SPECIFICATION

CURRENT RATING: 1.1 AMP MAX
DIELECTRIC WITHSTANDING: 500V AC FOR ONE MINUTE
CONTACT RESISTANCE: 30m OHMS MAX
INSULATION RESISTANCE: 1000M OHMS MIN AT DC 500V
OPERATION TEMPERATURE: -40°C~+85°C

TABLE

DIMENSIONS					
POS.	A	B	C	D	E
036	27.00	25.00	9.15	7.65	6.00
064	41.00	39.00	23.15	21.65	20.00
098	58.00	56.00	40.15	38.65	37.00
164	91.00	89.00	73.15	71.65	70.00



PART NUMBER:

MCEEE - * * * * T - 1 * B * * *

SERIES

NO. OF POS.
REF. TABLE

CONTACT PLATED OPTION

1: GOLD FLASH
3: 3u" GOLD
5: 5u" GOLD
6: 10u" GOLD
7: 15u" GOLD
9: 30u" GOLD

CAP & MYLAR OPTION
BLANK: WITHOUT CAP & MYLAR
C: WITH CAP
M: WITH MYLAR

RIDGE OPTION
BLANK: W/O RIDGE
R: WITH RIDGE

POST OPTION
BLANK: W/O POST
P: WITH POST

PACKAGE OPTION
1: TRAY
2: TAPE REEL

TIN PLATING ON SOLDER TAIL

A

A

B

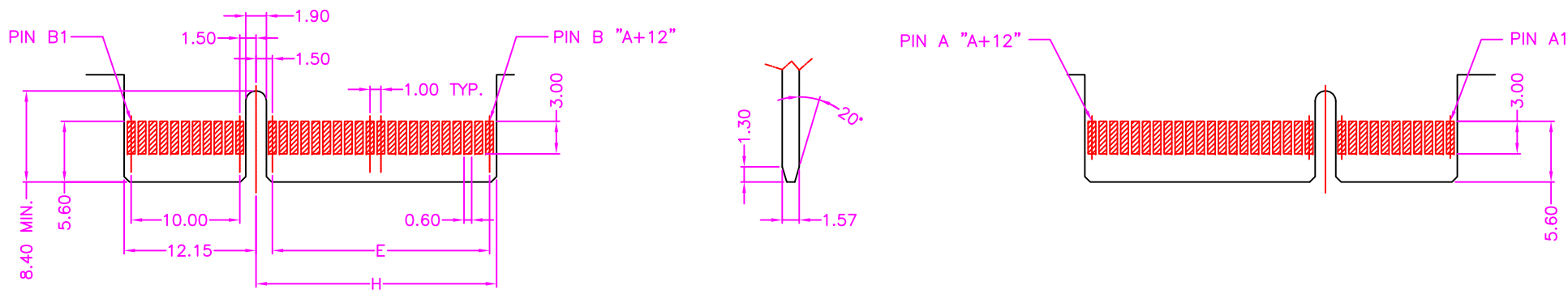
B

C

C

D

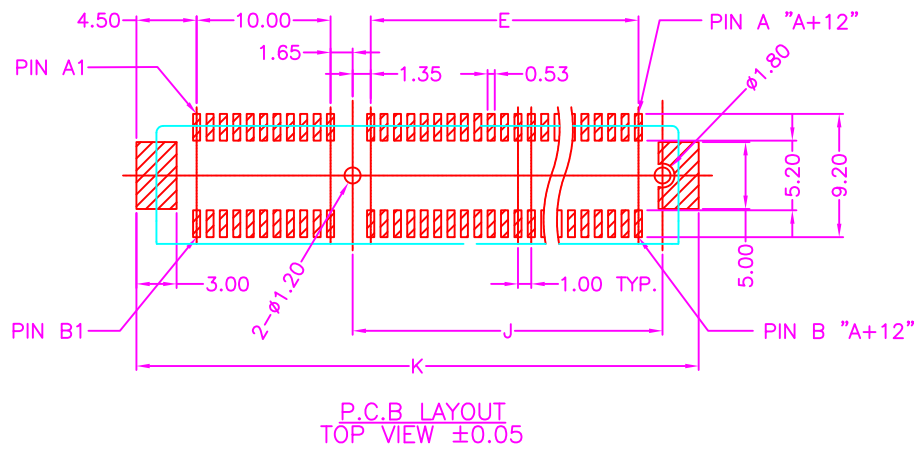
D



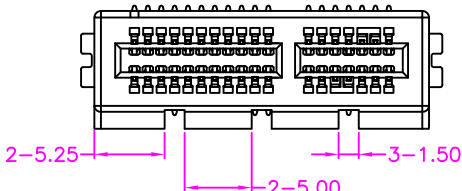
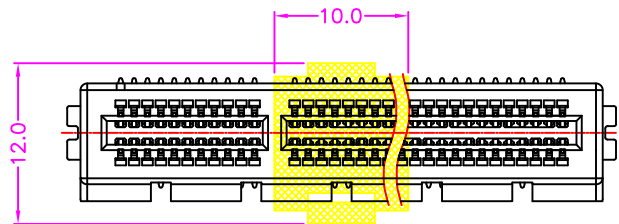
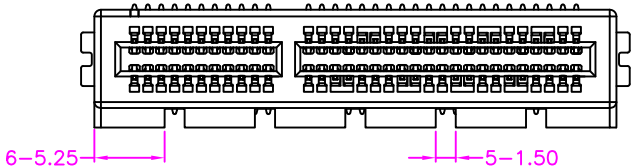
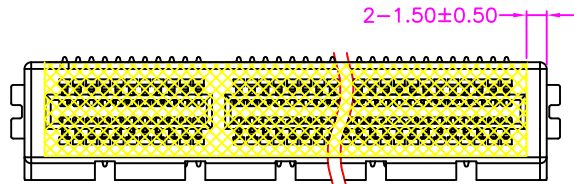
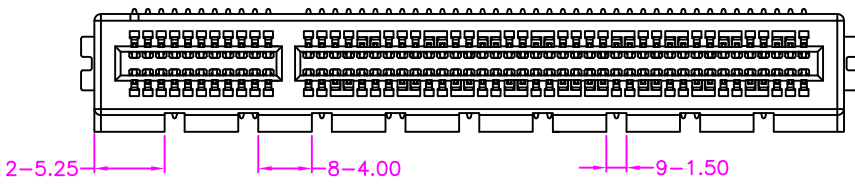
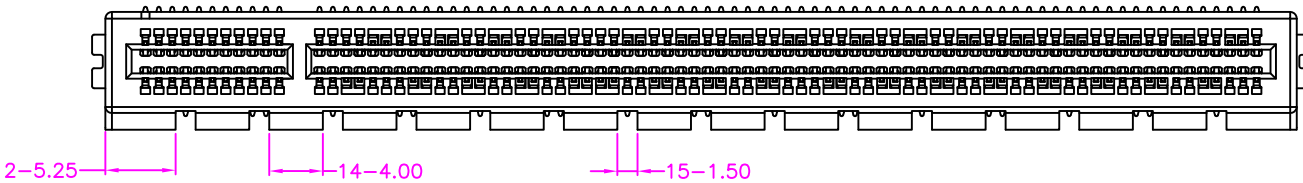
← I/O PANEL DIRECTION
PRIMARY (COMPONENT) SIDE

NOTES:
CHAMFER EDGE MUST BE FREE OF CUTTING BURRS

SECONDARY (SOLDER) SIDE



DIMENSIONS				
POS.	E	H	J	K
036	6.00	8.15	9.15	28.00
064	20.00	22.15	23.15	42.00
098	37.00	39.15	40.15	59.00
164	70.00	72.15	73.15	92.00

1	2	3	4	5	6
A	36 Pos. 			 WITH CAP	A
B	64 Pos. 			 WITH MYLAR	B
C	98 Pos. 				C
D	164 Pos. 				D
1	 ZICONN ELECTRONIC CO., LTD. WWW.ZICONN.COM 886-3-4687695	TOLERANCES X.±0.40 .XX±0.20 .X±0.30 .XXX±0.10	REV. A DRAWN BY Mika 2024/5/10 APPROVED BY Lion 2024/5/10	TITLE MCEEE-011 DRAW NO.	PCI EXPRESS GEN 5.0, 1.00mm PITCH, PCB MOUNT, SMT, 1 KEY, FEMALE UNIT MM Sheet 3/3
1	2	3	4	5	6